



Final Product/Process Change Notification

Document #:FPCN23597XO

Issue Date:19 Aug 2026

Title of Change:	Conversion of select onsemi, Czech Republic (Roznov) wafer fab technologies from 150mm to 200mm wafer diameter - MC33172 family.	
Proposed First Ship date:	26 Nov 2026 or earlier if approved by customer	
Contact Information:	Contact your local onsemi Sales Office	
PCN Samples Contact:	Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.	
Additional Reliability Data:	Contact your local onsemi Sales Office	
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. onsemi will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com	
Marking of Parts/ Traceability of Change:	The affected products will be identified with date code	
Change Category:	Wafer Fab Change	
Change Sub-Category(s):	Manufacturing Process Change	
Sites Affected:		
onsemi Sites	External Foundry/Subcon Sites	
onsemi Roznov, Czech Republic	None	
Description and Purpose:		
Conversion of select onsemi Czech Republic (Roznov) wafer fab technologies from 150mm to 200mm wafer diameter.		
The purpose is to increase the wafer fab productivity.		
The 200mm wafer process is being created at Roznov to get the same electrical and reliability performances as the 150mm process.		
This is a change in wafer diameter only; there will be no changes to assembly or test locations as a result of this change.		
	From	To
Wafer size	150 mm	200 mm
There is no product marking change as a result of this change		



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Reliability Data Summary:

QV DEVICE NAME: MC33274ADTBR2G

RRF#: 100944

PACKAGE: TSSOP14

Test	Specification	Condition	Interval	Result
HTOL	JESD22 A108	Ta= 110°C	1008 hrs	0/80
HAST	JESD22 A110	110°C/85%	264 hrs	0/240
PC	JESD22 A113 J-STD-020	SMD only, Test MSL=1, @260°C		Pass
TC	JESD22 A104	Ta= -65°C to +150°C	500cyc	0/240

QV DEVICE NAME : ULN2003ADR2G

RMS# 68977

PACKAGE: SOIC16

Test	Specification	Condition	Interval	Results
HTOL	JA108	Ta= 125°C	2016 hrs	0/240
PC	JA112 JA113	SMD only, Test MSL=1, @260°C		0/372
ELFR	JA018	Ta = 125°C for 48 hrs	48hrs	0/2400
TC	JA104	Ta= -65°C to +150°C	1000cyc	0/270
ESD HBM	AEC-Q100-002	c = 0, Test @ R	2kV	0/3
ESD CDM	AEC-Q100-011	c = 0, Test @ R	1.5kV	0/3
ED	ON Data Sheet	Cpk > 1.67 Test @ R, H, C	Cpk>1.67	pass
LU	AEC-Q100-004	Test @ EP; Test & Stress @ R	LU+>100mA LU->100mA	0/6

Electrical Characteristics Summary:

Electrical characteristics are not impacted.

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [**PCN Customized Portal**](#).

Current Part Number	New Part Number	Qualification Vehicle
MC33172VDR2G	#NONE	MC33274ADTBR2G, ULN2003ADR2G
MC33172DR2G	#NONE	MC33274ADTBR2G, ULN2003ADR2G

PCN Product List Addendum for:

Customer Contact Name: Premier Farnell Dropbox

Customer Contact Email: productchangenotices@newark.com

Appendix A: Changed Products

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NWKC: PREMIER FARNELL

Product	Customer Part Number	Qualification Vehicle	New Part Number	Replacement Supplier
MC33172DR2G	1651873	MC33274ADTBR2G, ULN2003ADR2G	#NONE	
MC33172VDR2G	2728396	MC33274ADTBR2G, ULN2003ADR2G	#NONE	